



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D

*\* : Required Field*

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2015-05-07
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Flavio Di Francesco	<b>Representative Title</b>	AMS Materials Declaration Champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**


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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	ED6R*V634BRL	A	BO2A	2015-05-07
Amount	UoM	Unit type	ST ECOPACK Grade	
54.82	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
D50	5 -4.4 -0.9	14	gull wing	
Comment	Package: TSSOP 14 BODY 4.4 PITCH 0.65; Md valid for TSV634AIPT			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	<b>true</b>
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description

QueryList : ELV directive : 2000/53/EC amended 2013/28/EU _ May 2013	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	<b>true</b>
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Exemption Id.	Description
	#N/A

QueryList : REACH-17th December 2014				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				<b>true</b>
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	ED6R*V634BRL					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies (choose)	Other inorganic materials	1.178	mg	supplier	die	Silicon (Si)	7440-21-3		1.139	mg	966893	20777
				supplier	metallization	Aluminium (Al)	7429-90-5		0.010	mg	8489	182
				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	849	18
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	849	18
				supplier	Passivation	Silicon Nitride	12033-89-5		0.003	mg	2547	55
				supplier	Passivation	Silicon Oxide	7631-86-9		0.024	mg	20374	438
Leadframe	Copper & its alloys	25.529	mg	supplier	alloy	Copper (Cu)	7440-50-8		24.545	mg	961456	447738
				supplier	alloy	Nickel (Ni)	7440-02-0		0.765	mg	29966	13955
				supplier	alloy	Magnesium (Mg)	7439-95-4		0.038	mg	1489	693
				supplier	alloy	Silicon (Si)	7440-21-3		0.166	mg	6502	3028
				supplier	metallization	Nickel (Ni)	7440-02-0		0.014	mg	548	255
				supplier	metallization	Palladium (Pd)	7440-05-3		0.001	mg	39	18
Die attach	Other inorganic materials	0.386	mg	supplier	glue or tape (choose)	Silver (Ag)	7440-22-4		0.294	mg	761658	5363
				supplier	glue or tape	2,6-Diglycidylphenyl allyl ether	13561-08-5		0.039	mg	101036	711
				supplier	glue or tape	2,6-Diglycidyl phenyl allyl ether	CE 417-470-1		0.023	mg	59585	420
				supplier	glue or tape	1,4-bis (2,3-epoxypropoxy) butane	2425-79-8		0.015	mg	38860	274
				supplier	glue or tape	Polyoxypropylenediamine	9046-10-0		0.015	mg	38860	274
Bonding wires	Precious Metals	0.243	mg	supplier	wire	Gold (Au)	7440-57-5		0.243	mg	1000000	4433
Encapsulation	Other Organic Materials	27.484	mg	supplier	mold compound	Amorphous silica	7631-86-9		21.987	mg	799993	401076
				supplier	mold compound	epoxy resin	Proprietary		4.535	mg	165005	82725
				supplier	mold compound	Antimony Trioxide	1309-64-4		0.550	mg	20012	10033
				supplier	mold compound	Brominated flame retardant	Proprietary		0.275	mg	10006	5016
				supplier	mold compound	Carbon Black	1333-86-4		0.137	mg	4985	2499